



参考資料 Vishay Siliconix

N-Channel 20-V (D-S) MOSFETs

PRODUCT SUMMARY			
V _{DS} (V)	$r_{DS(on)}$ (Ω)	I _D (A)	
20	0.4 at $V_{GS} = 4.5 \text{ V}$	0.73	
	0.5 at V _{GS} = 2.5 V	0.65	

FEATURES

• TrenchFET® Power MOSFET

ESD Protected: 4000 V



COMPLIANT

APPLICATIONS

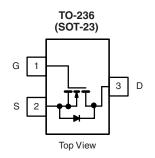
• Direct Logic-Level Interface: TTL/CMOS

• Drivers: Relays, Solenoids, Lamps, Hammers

Battery Operated Systems, DC/DC Converters

Solid-State Relays

• Load/Power Switching-Cell Phones, Pagers

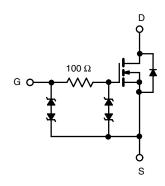


Marking Code: K2ywl

K2 = Part Number Code for TN0200K

y = Year Code w = Week Code I = Lot Traceability

Ordering Information: TN0200K-T1-E3 (Lead (Pb)-free)



ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V_{DS}	20	V	
Gate-Source Voltage		V _{GS}	± 8		
Continuous Drain Current /T 150 °C\b	T _A = 25 °C	I_	0.73		
Continuous Drain Current (T _J = 150 °C) ^b	T _A = 70 °C	I _D	0.58		
Pulsed Drain Current ^a		I _{DM}	4	Α	
Continuous Source Current (Diode Conduction) ^b		l _S 0.3		7	
Bound Biodination b	T _A = 25 °C	P _D	0.35	W	
Power Dissipation ^b	T _A = 70 °C	' D	0.22	V V	
Operating Junction and Storage Temperature Range		T _{J,} T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Maximum Junction-to-Ambient ^b	R _{thJA}	357	°C/W	

- a. Pulse width limited by maximum junction temperature.
- b. Surface Mounted on FR4 Board, $t \le 10$ sec.

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参考資料



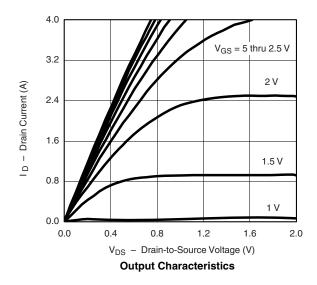
SPECIFICATIONS T _A = 25 °C, unless otherwise noted							
		Test Conditions	Limits				
Parameter	Symbol		Min	Тур	Max	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 10 μA 20				V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 50 \mu A$	0.45	0.6	1.0	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 5		
Zero Gate Voltage Drain Current	la a a	V _{DS} = 20 V, V _{GS} = 0 V			0.1	μΑ	
	I _{DSS}	T _J = 55 °C			10		
0.01.0.13		$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	2.5			A	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 2.5 \text{ V}$	1.5				
	Y	$V_{GS} = 4.5 \text{ V}, I_D = 0.6 \text{ A}$		0.2	0.4	Ω	
Drain-Source On-Resistance ^a	r _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 0.6 \text{ A}$		0.25	0.5		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 5 V, I _D = 0.6 A		2.2		S	
Diode Forward Voltage ^a	V _{SD}	$I_S = 0.3 \text{ A}, V_{GS} = 0 \text{ V}$		0.8	1.2	V	
Dynamic ^b	<u>.</u>						
Total Gate Charge	Q _g	V 40.V.V 4.F.V		1400	2000	pC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}$ $I_D = 0.6 \text{ A}$		190			
Gate-Drain Charge	Q _{gd}			300			
Gate Resistance	R _g			105		Ω	
Turn-On Delay Time	t _{d(on)}	$V_{DD} = 10 \text{ V}, R_L = 16 \Omega$ $I_D \cong 0.6 \text{ A}, V_{GEN} = 4.5 \text{ V}$ $R_g = 6 \Omega$		17	25	ns	
Rise Time	t _r			20	30		
Turn-Off Delay Time	t _{d(off)}			55	85		
Fall Time	t _f			30	45		

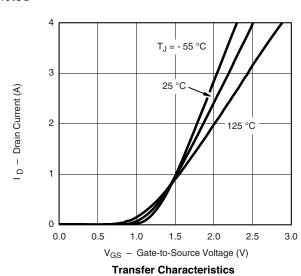
Notes:

- a. Pulse test: PW \leq 300 μs duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



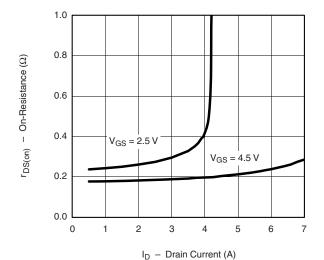




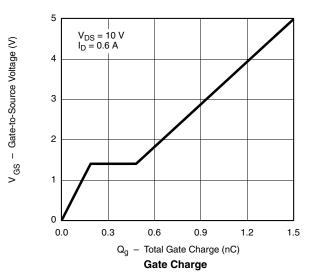
参考資料

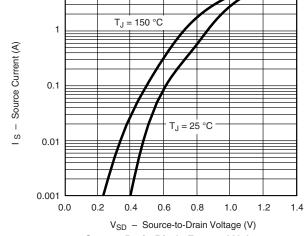
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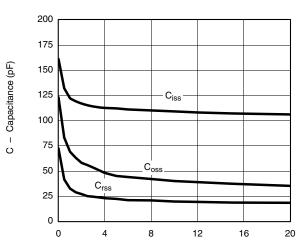


On-Resistance vs. Drain Current

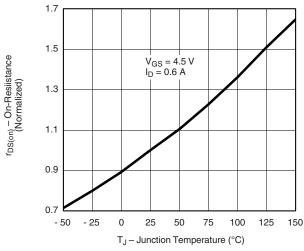




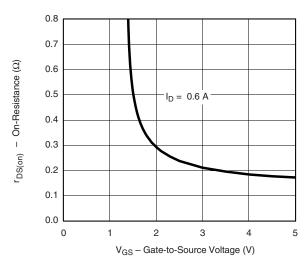
Source-Drain Diode Forward Voltage



V_{DS} - Drain-to-Source Voltage (V) **Capacitance**



On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-Source Voltage

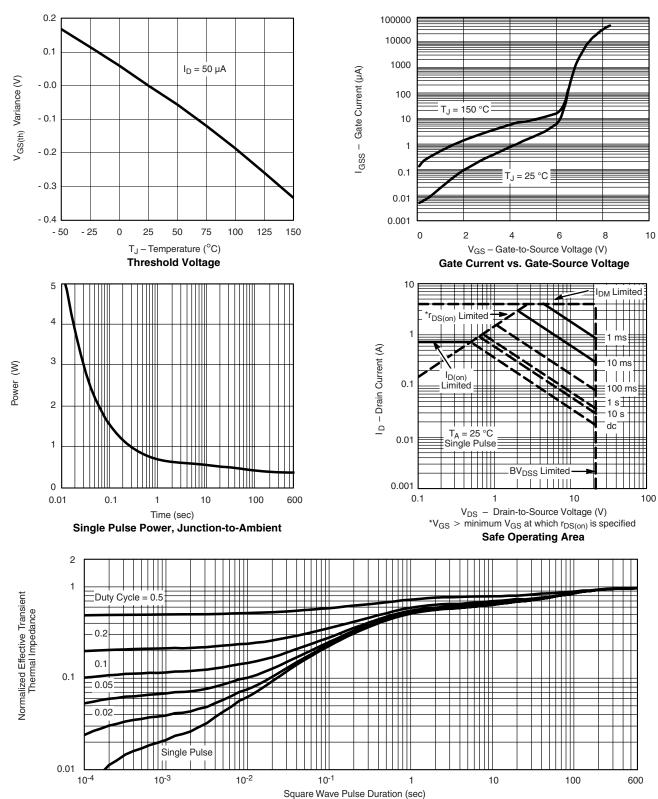
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Effective Transient Thermal Impedance, Junction-to-Ambient

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